

WHAT IS CLAIMED IS:

1. A light-emitting device, comprising:

a first substrate having a luminous element and a first group of wirings electrically connected to the luminous element;

a second substrate having a terminal portion and a second group of wirings electrically connected to the terminal portion; and

a conductor for electrically connecting said first group of wirings and said second group of wirings.

2. A device according to claim 1, wherein said luminous element is an EL element.

3. A device according to claim 1, wherein said second group of wirings are made of a metallic film selected from the group consisting of copper, silver, gold, aluminum and nickel, or an alloy film containing as a main component a material selected from the group consisting of copper, silver, gold, aluminum, and nickel.

4. A device according to claim 1, wherein said second group of wirings are formed into a layered structure made of a metallic film that is made of two or more different elements selected from copper, silver, gold, aluminum and nickel.

5. A device according to claim 1, wherein said second group of wirings are formed on a front surface of said second substrate, on a back surface thereof, or in the interior thereof.

6. A device according to claim 1, wherein a via hole that is covered

by said second group of wirings is formed in said second substrate.

7. A light-emitting device, comprising:

a first substrate having a luminous element and a first group of wirings electrically connected to the luminous element;

a second substrate having a terminal portion and a second group of wirings electrically connected to the terminal portion;

a conductor for electrically connecting said first group of wirings and said second group of wirings; and

a sealing agent for bonding said first substrate and said second substrate together.

8. A device according to claim 7, wherein said luminous element is an EL element.

9. A device according to claim 7, wherein said second group of wirings are made of a metallic film selected from the group consisting of copper, silver, gold, aluminum and nickel, or an alloy film containing as a main component a material selected from the group consisting of copper, silver, gold, aluminum, and nickel.

10. A device according to claim 7, wherein said second group of wirings are formed into a layered structure made of a metallic film that is made of two or more different elements selected from copper, silver, gold, aluminum and nickel.

11. A device according to claim 7, wherein said second group of wirings are formed on a front surface of said second substrate, on a back surface thereof, or in the interior thereof.

12. A device according to claim 7, wherein a via hole that is covered by said second group of wirings is formed in said second substrate.

13. A light-emitting device, comprising:

a first substrate having a luminous element and a first group of wirings electrically connected to the luminous element;

a second substrate having a terminal portion and a second group of wirings electrically connected to the terminal portion;

a conductor for electrically connecting said first group of wirings and said second group of wirings;

a sealing agent for bonding said first substrate and said second substrate together; and

a resin filled in a space between said first substrate and said second substrate.

14. A device according to claim 13, wherein said luminous element is an EL element.

15. A device according to claim 13, wherein said second group of wirings are made of a metallic film selected from the group consisting of copper, silver, gold, aluminum and nickel, or an alloy film containing as a main component a material selected from the group consisting of copper, silver, gold, aluminum, and nickel.

16. A device according to claim 13, wherein said second group of wirings are formed into a layered structure made of a metallic film that is made of two or more different elements selected from copper, silver, gold, aluminum and nickel.

17. A device according to claim 13, wherein said second group of wirings are formed on a front surface of said second substrate, on a back surface thereof, or in the interior thereof.

18. A device according to claim 13, wherein a via hole that is covered by said second group of wirings is formed in said second substrate.